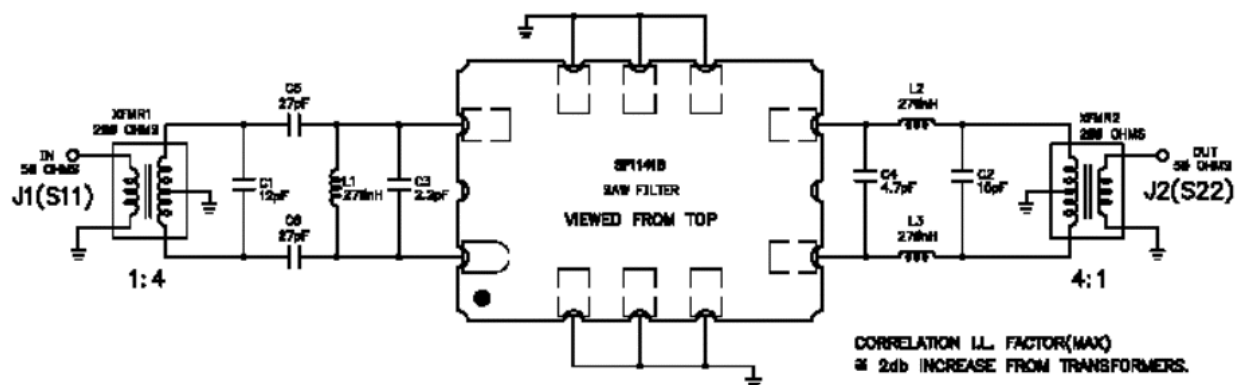


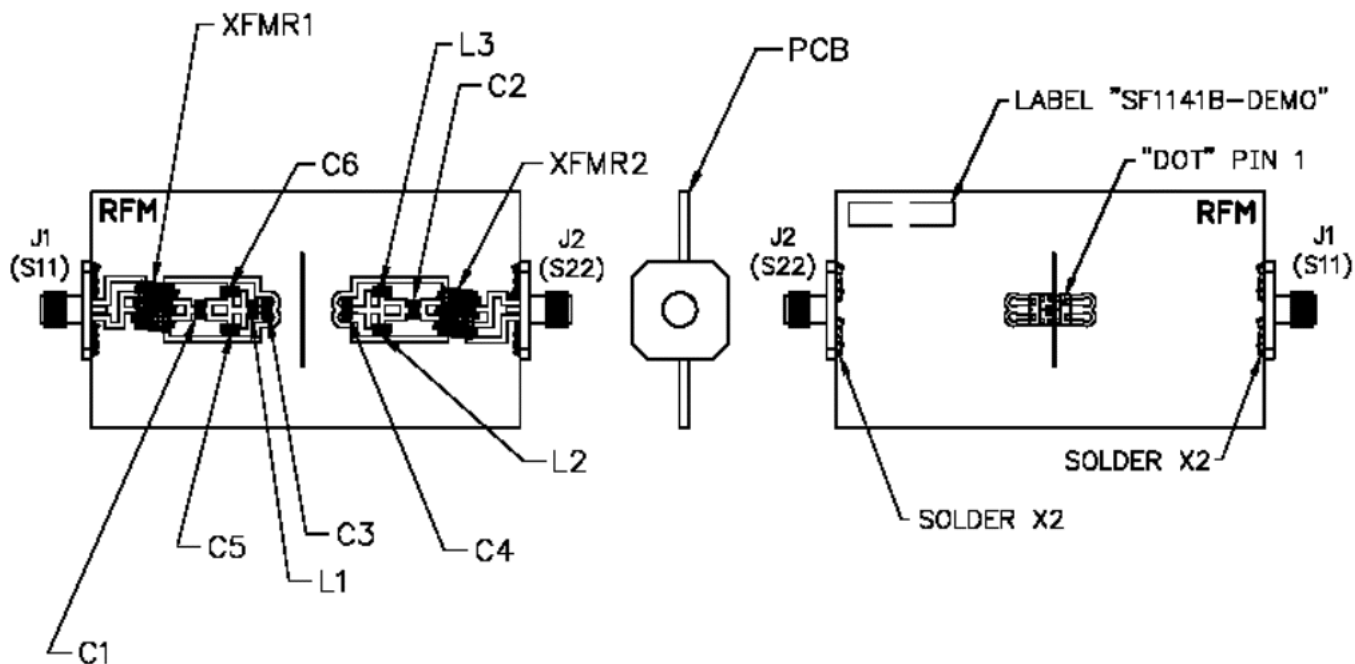
NOTES:

- 1 USE A WRIST STRAP WHEN SOLDERING TRANS 1, AND TRANS 2 TO PCB.
(CUT LEADS .87 IN.)
- 2 MOUNT AND SOLDER ALL COMPONENTS ON PCB.
- 3 CUT CENTER CONDUCTORS FROM J1 AND J2 TO .18 IN.
- 4 MOUNT J1 AND J2 AS SHOWN (SOLDER BACKSIDE ALSO).
- 5 LABEL DEMO BOARD ACCORDINGLY.
- 6 MOUNT "FILTER" ON TOPSIDE OF PCB AS SHOWN.

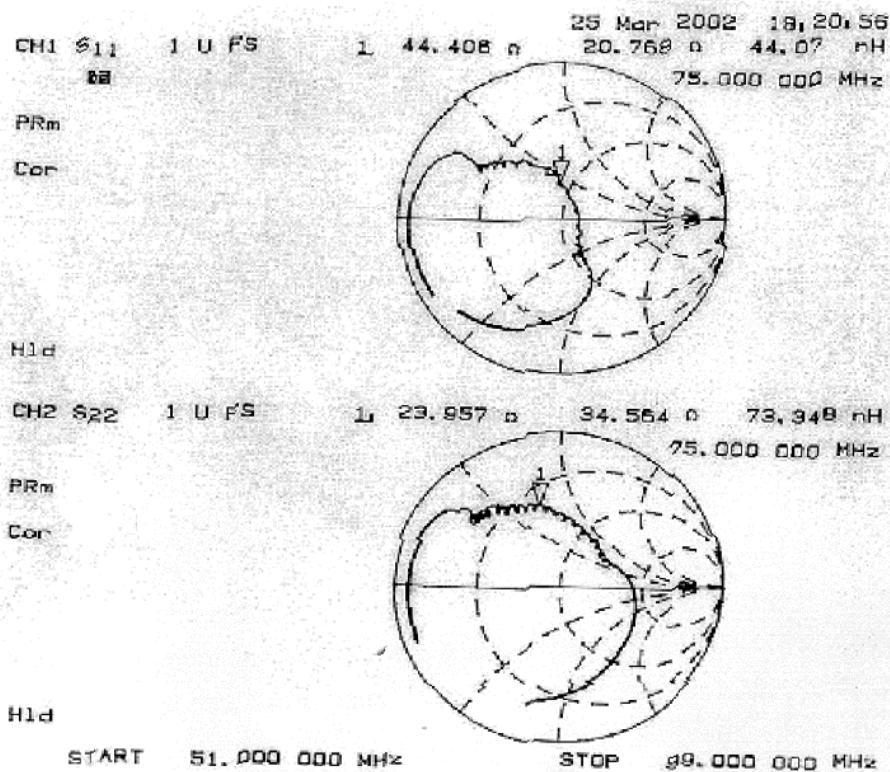
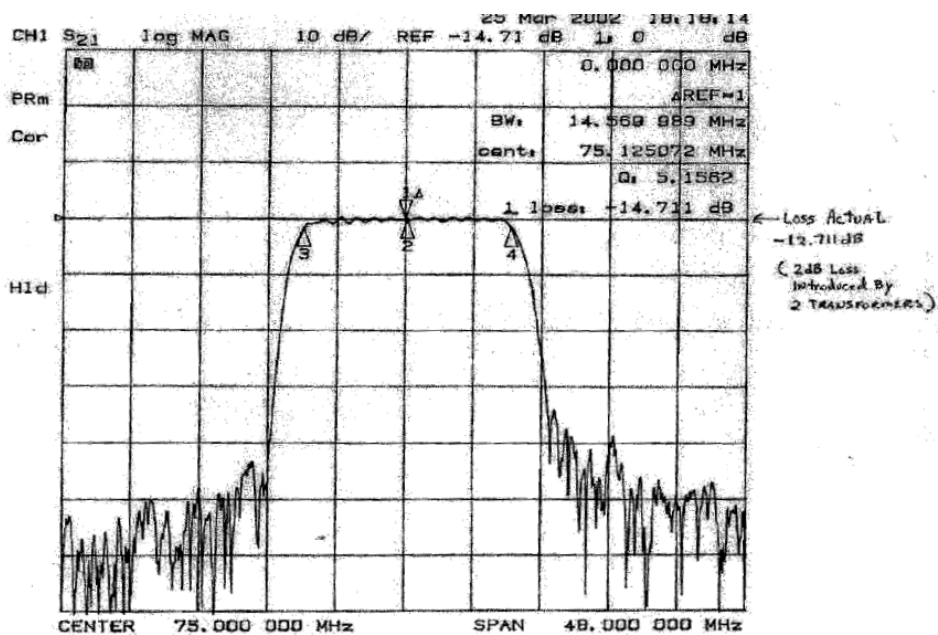
REV	SIZE	DESCRIPTION	DATE
A	9248	INITIAL RELEASE	11dec88
B	18658	REVISED	30apr92
C	11876	REVISED	28nov92

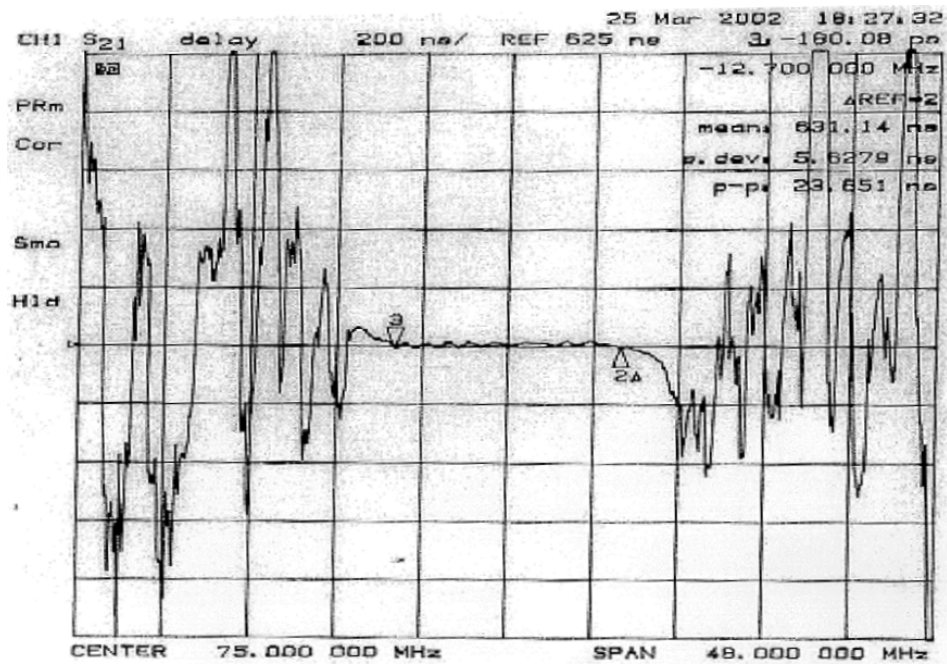


TITLE				
ASSY DIAGRAM, DEMO BOARD, SF1141B, S, TD				
SIZE	FORM NO.	ORIG. NO.	REV	SHEET
B	2U874	SF1141B-186	C	1/2

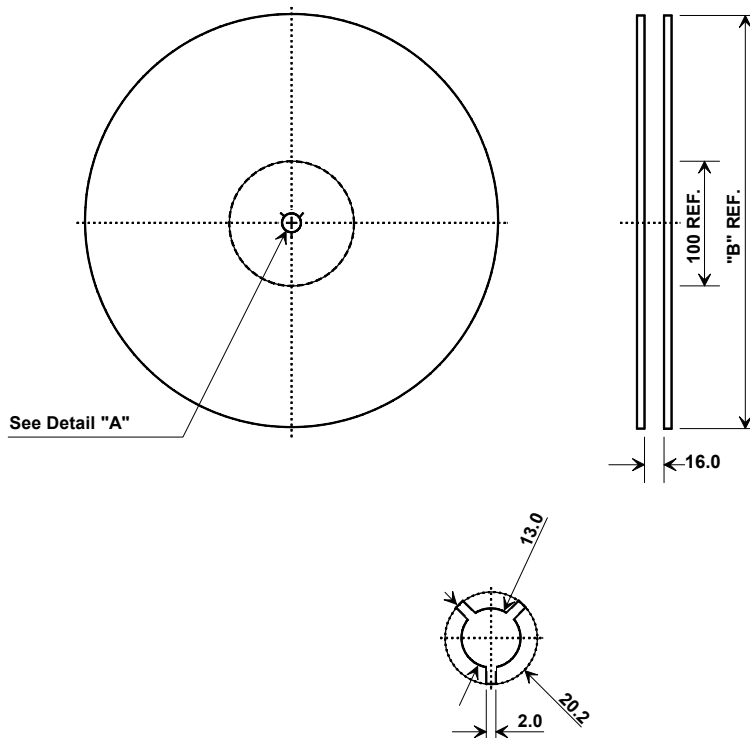


SIZE	FORM NO.	ORIG. NO.	REV	SHEET
B	2U874	SF1141B-186	C	2



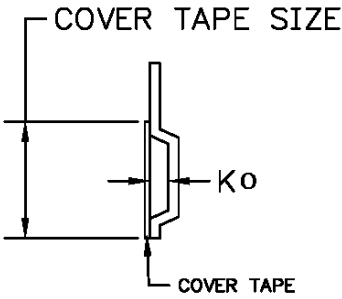


Tape and Reel Specifications

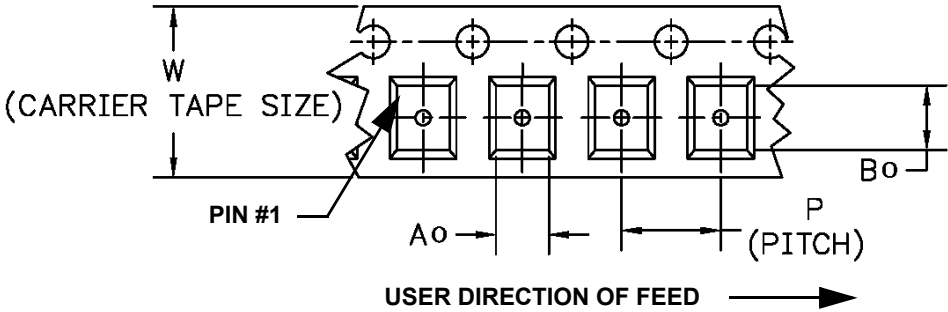


"B "		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

COMPONENT ORIENTATION and DIMENSIONS

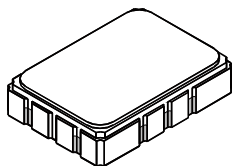


Carrier Tape Dimensions		Tolerance
Ao	5.5 mm	± 0.1mm
Bo	7.5 mm	± 0.1mm
Ko	2.0 mm	± 0.1mm
Pitch	8.0 mm	± 0.1mm
W	16.0 mm	± 0.2mm

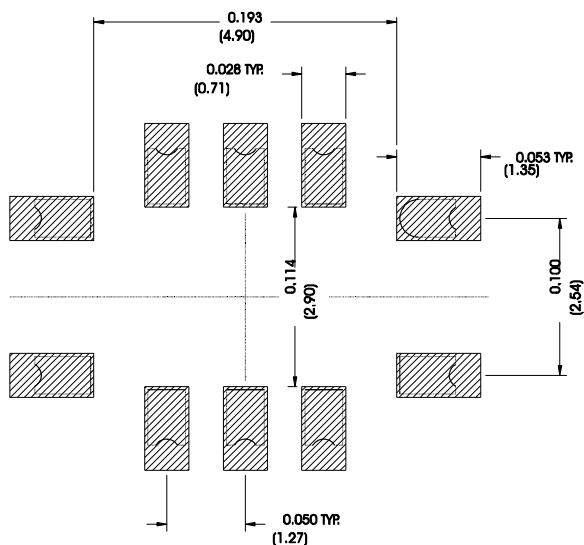


SMP-03 Case

10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

